

Bill of Materials

TI DESIGNS

TIDC-WIFI-METER-READING (CC3200MOD)

Item #	Quantity	Designator	Value	Description	Manufacturer	PartNumber	Footprint	Component Link URL
1	1	PCB		Printed Circuit Board	Any	TIDM-CC3200MOD_CONV		
2	1	ANT	2.45-GHz Ant	Chip antenna	Taiyo Yuden	AH316M245001-T	AH316M	Taiyo Yuden
3	1	C1	1pF	CAP, CERM, 1 pF, 50 V, +/- 10%,	MuRata	GRM1555C1H1R0BA01D	0402	MuRata
4	2	C2, C3	100uF	CAP, CERM, 100 µF, 6.3 V, +/- 20%, X5R, 1210	MuRata	GRM32ER60J107ME20L	1210	MuRata
5	1	C4	DNP	CAP, CERM, 10 pF, 50 V, +/- 5%,	MuRata	GRM1555C1H100JA01D	0402	MuRata
6	1	D1	DFLS160	Diode, Schottky, 1A, 60V	Diodes	DFLS160	POWERDI_123	Diodes
7	1	J1		Header, 4-Pin		3-644456-4	HDR1X4	
8	1	J2		Header, 4-Pin		3-644456-4	HDR1X4	
9	1	J3		Connector, Ultra-Mini Coaxial, SMD	Hirose Electric Co. Ltd.	U.FL-R-SMT-1	CONN_UFL-R-SMT-1	Hirose Electric Co. Ltd.
10	1	J4	MM8030-2600RJ3	Connector, Microwave, 50 Ohm Coax	murata	MM8030-2600RJ3	CONN_MICRO-MM8030-2600	murata
11	1	L1	3.6nH	Inductor, Film, 3.6 nH, 0.1 A, 1.3	MuRata	LQP15MN3N6B02D	LQP_0402	MuRata
12	1	L2	DNP	Inductor, Film, 3.6 nH, 0.1 A, 1.3 ohm, SMD	MuRata	LQP15MN3N6B02D	LQP_0402	MuRata
13	1	LBL1		Thermal Transfer Printable Labels,	Brady	THT-14-423-10	Label_650x200	Brady
14	1	LED1		Red	Liteon	LTST-C170KRKT	0805-LED	Liteon
15	1	LED2		Green	Liteon	LTST-S220KGKT	0805-LED	Liteon
16	1	LED3		Blue	Liteon	LTST-C170TBKT	0805-LED	Liteon
17	3	Q1, Q2, Q3	50V	MOSFET, N-CH, 50 V, 0.22 A, SOT-	Fairchild Semiconductor	BSS138	SOT-23	Fairchild Semiconductor
18	6	R2, R7, R9, R20, R39, R59	0	RES, 0, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED	0402	Vishay-Dale
19	23	R3, R5, R11, R13, R15, R17, R22, R23, R24, R25, R26, R27, R29, R31, R32, R33, R34, R35, R36, R37, R38, R40, R58	DNP	RES, DNP, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED (Phantom)	0402	Vishay-Dale
20	3	R41, R42, R43	390	RES, 390, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402390RJNED	0402	Vishay-Dale
21	4	R44, R45, R47, R56	100k	RES, 100 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402100KJNED	0402	Vishay-Dale
22	1	R46	2.7k	RES, 2.7 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04022K70JNED	0402	Vishay-Dale
23	1	R48	100	RES, 100, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402100RJNED	0402	Vishay-Dale
24	2	R49, R51	1.0k	RES, 1.0 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04021K00JNED	0402	Vishay-Dale
25	5	R50, R52, R53, R54, R55	10k	RES, 10 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040210K0JNED	0402	Vishay-Dale
26	1	R57	0	RES, 0, 5%, 0.125 W, 0805	Vishay-Dale	CRCW08050000Z0EA	0805_HV	Vishay-Dale
27	2	RF1B, RF2B	SFM-110-02-SM-D-A-K-TR	Header, SMT 10X2 pin, Shrouded	Samtec	SFM-110-02-SM-D-A-K-TR	HEADER_TFM-110-02-SM	Samtec
28	2	RF1T, RF2T		CONN SHRD HDR HDR 20 POS 1.27MM SLDR ST SMD	Samtec	TFM-110-02-S-D-A-K-TR	Samtec_TFM-110-02-S-D-A-K	Samtec
29	3	S1, S2, S3		Switch, Tactile, SPST-NO, 0.05A,	TE Connectivity	4-1437565-1	SW_FSM4JSMA	TE Connectivity
30	1	SOP		Switch, SPST, 4 Pos, Top Actuated, SMD	TE Connectivity	1571983-5	SW_1571983-5	TE Connectivity
31	1	U1			Texas Instruments	CC3200MOD	CC3200MOD	Texas Instruments

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